

SUBSTITUTE ABSTRACT

The present application is directed to various methods for forming a patterned thin film on a substrate by causing a specific fluid to adhere. More particularly, this application describes a method for manufacturing a substrate by forming a metal layer on a base, removing a part of the metal layer by supplying energy to form a pattern non-formation region comprised of the metal layer pattern non-formed region and a pattern formation region comprised of a metal layer pattern formed region and a base exposed region, forming a sulfur compound film on the metal layer pattern unformed region and the metal layer pattern formed region by immersing the base in a liquid containing a sulfur compound and forming a thin film pattern on the pattern formation region by applying a fluid to the pattern formation region that exhibits a non-affinity to the sulfur compound film and an affinity to the base.